FY2025 Third Quarter
（Ended November 30, 2025）
Financial Briefing

January 9, 2026
RORZE CORPORATION

（Code：6323）
https://www.rorze.com/ir

Disclaimer

◆ Regarding forward-looking statements

The business forecasts and other forward-looking statements contained in this document are based on judgments made in accordance with information currently available for our company and do not constitute a guarantee or promise of the accuracy or completeness of such information. The forecast is also subject to change without notice due to changes in economic conditions, industry competition, markets and other systems.

◆ Data included in this document are stated as follows

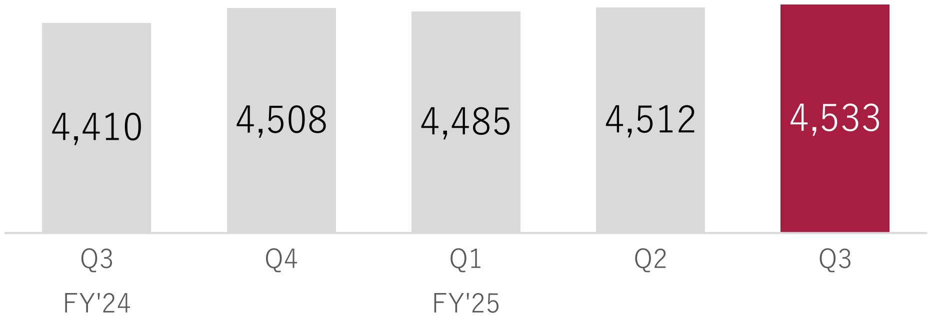
JPY values	：	Rounded down to the nearest unit
Percentages	：	Rounded to the nearest unit after calculated in units of 1 JPY
Fiscal year	：	Refer to the "fiscal year ended February 28, 2026" as "FY2025" or "FY'25,"
Accounting period	：	The accounting periods of the consolidated, domestic companies and overseas subsidiaries are as follows:

	Q1 (1st Quarter)	Q2 (2nd Quarter)	Q3 (3rd Quarter)	Q4 (4th Quarter)	Full-year
Consolidated and domestic companies	Mar.～May.	Jun.～Aug.	Sep.～Nov.	Dec.～ The following Feb.	Mar.～ The following Feb.
Overseas subsidiaries	Jan.～Mar.	Apr.～Jun.	Jul.～Sep.	Oct.～Dec.	Jan.～Dec.

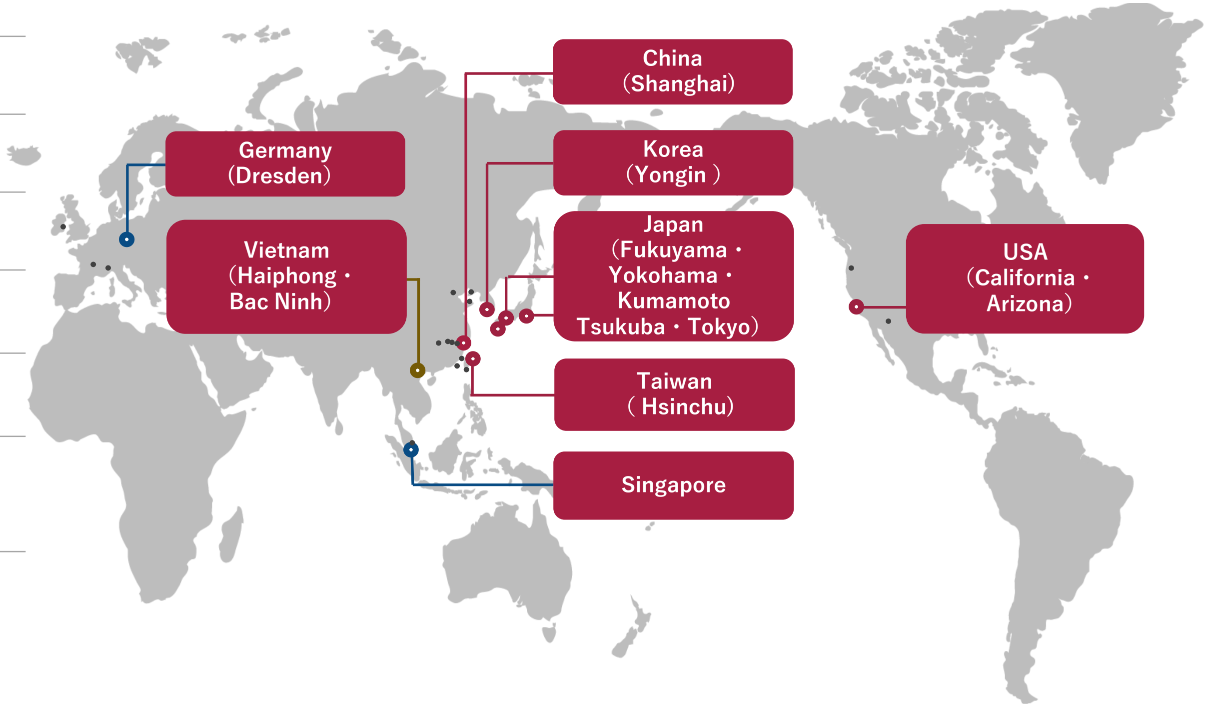
Company Profile

Name	RORZE CORPORATION
Listed Market	Tokyo Stock Exchange Prime Market (Securities code：6323)
Head Office	Kannabe-cho, Fukuyama-shi, Hiroshima
Head Office	March 30, 1985
Capital	982 million JPY
Business	Development, design, manufacturing, and sales of automation system for semiconductor/FPD production and life science automation products
Employees ※	Consolidated： 4,533 Non-consolidated： 363 (As of November 30, 2025)
Locations	Japan : Fukuyama, Yokohama, Kumamoto, Tsukuba and Tokyo Overseas : USA, Vietnam, Taiwan, Korea, Singapore, China , Germany and France

Number of employees (Consolidated) ※



Global Network



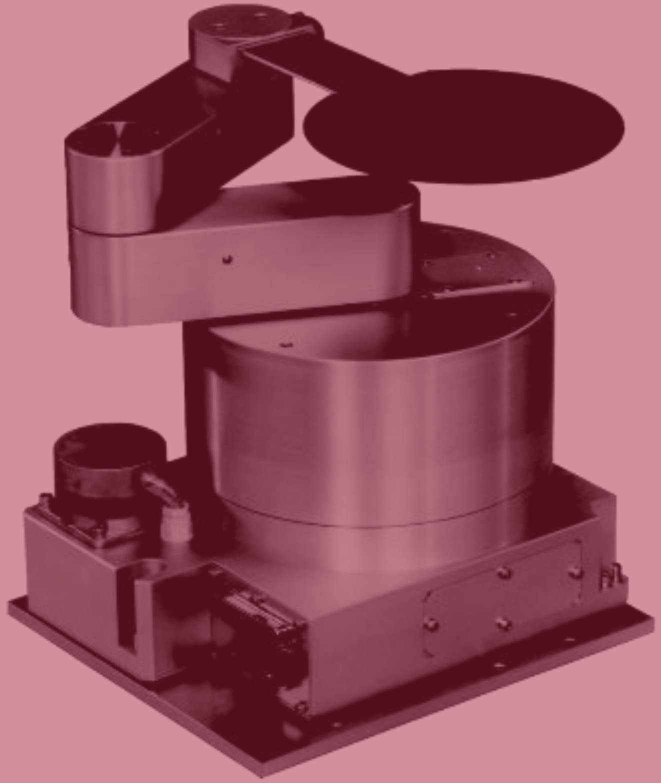
● R&D, Manufacturing, Sales, Support

● Sales, Support

● R&D, Manufacturing

• Support

※Starting from Q3 FY2025, the number of employees includes the annual average headcount of temporary and rehired employees, and past data have been updated accordingly



FY2025
Third Quarter
(March 1 ～November 30, 2025)
Consolidated Business Results

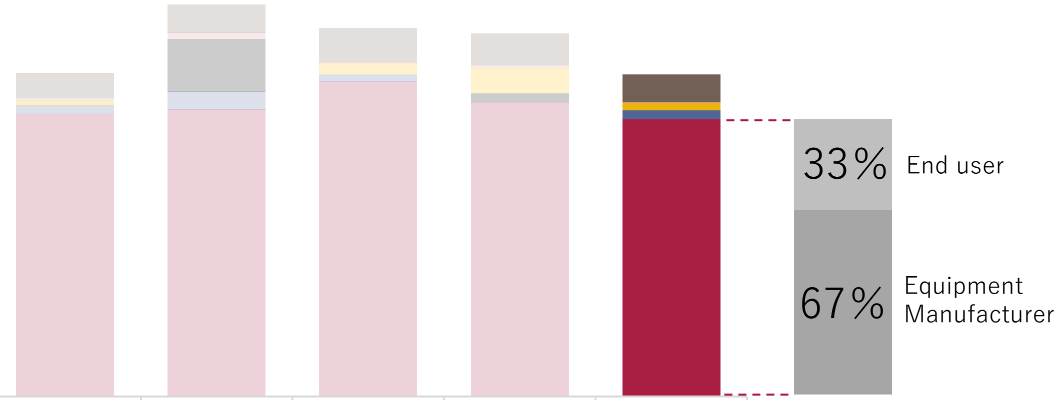
Summary of Q3 FY2025

- Sales grew 6% YoY, while quarterly sales from major customers in Taiwan and equipment manufacturers in China temporarily declined
- Operating profit declined 8% YoY, reflecting the costs of the subsidiary consolidated from Q3 FY2024 while gross profit increased 6%
- Ordinary profit declined 13% YoY, impacted by a non-operating change from foreign exchange gains to losses through the valuation of balance sheet items including intercompany loans (▲ 1.6 billion JPY YoY)

(Million JPY)

	FY’25 Q3	FY’24 Q3	YoY
Net sales	94,483	89,236	105.9%
Semi	79,544	76,628	103.8%
Analysis device ※	2,210	1,978	111.7%
FPD	3,949	3,888	101.6%
Life science	469	506	92.7%
Service/Parts etc. ※	8,310	6,234	133.3%
Operating profit	23,532	25,593	91.9%
Ordinary profit	23,375	26,762	87.3%
Profit attributable to owners of parent	17,465	19,708	88.6%
Average rate for the period (JPY/USD)	148	150	—

Quarterly Sales Trends

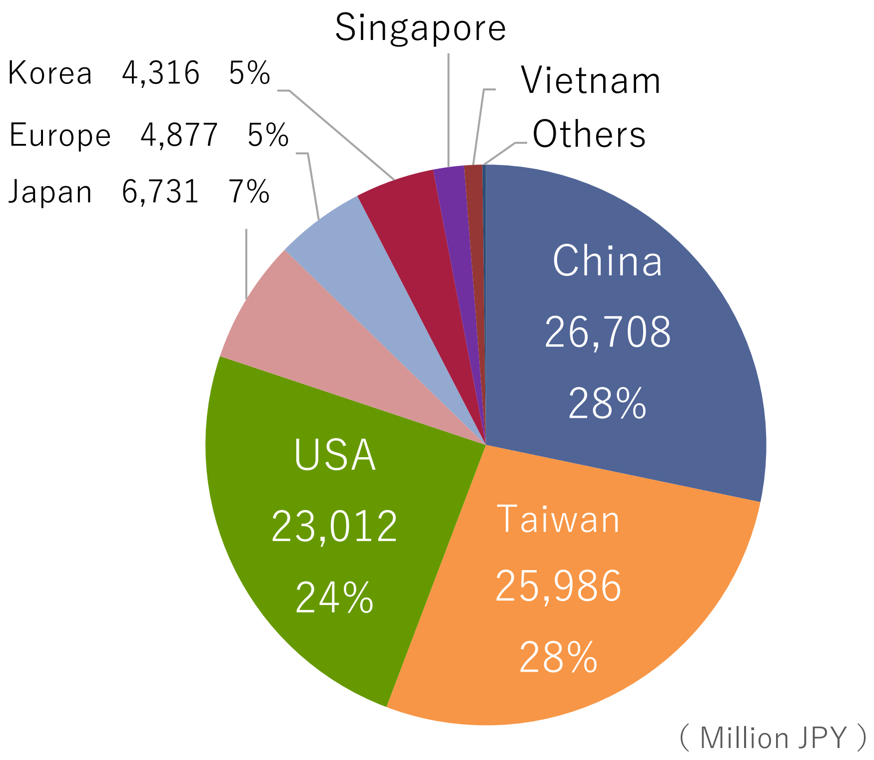


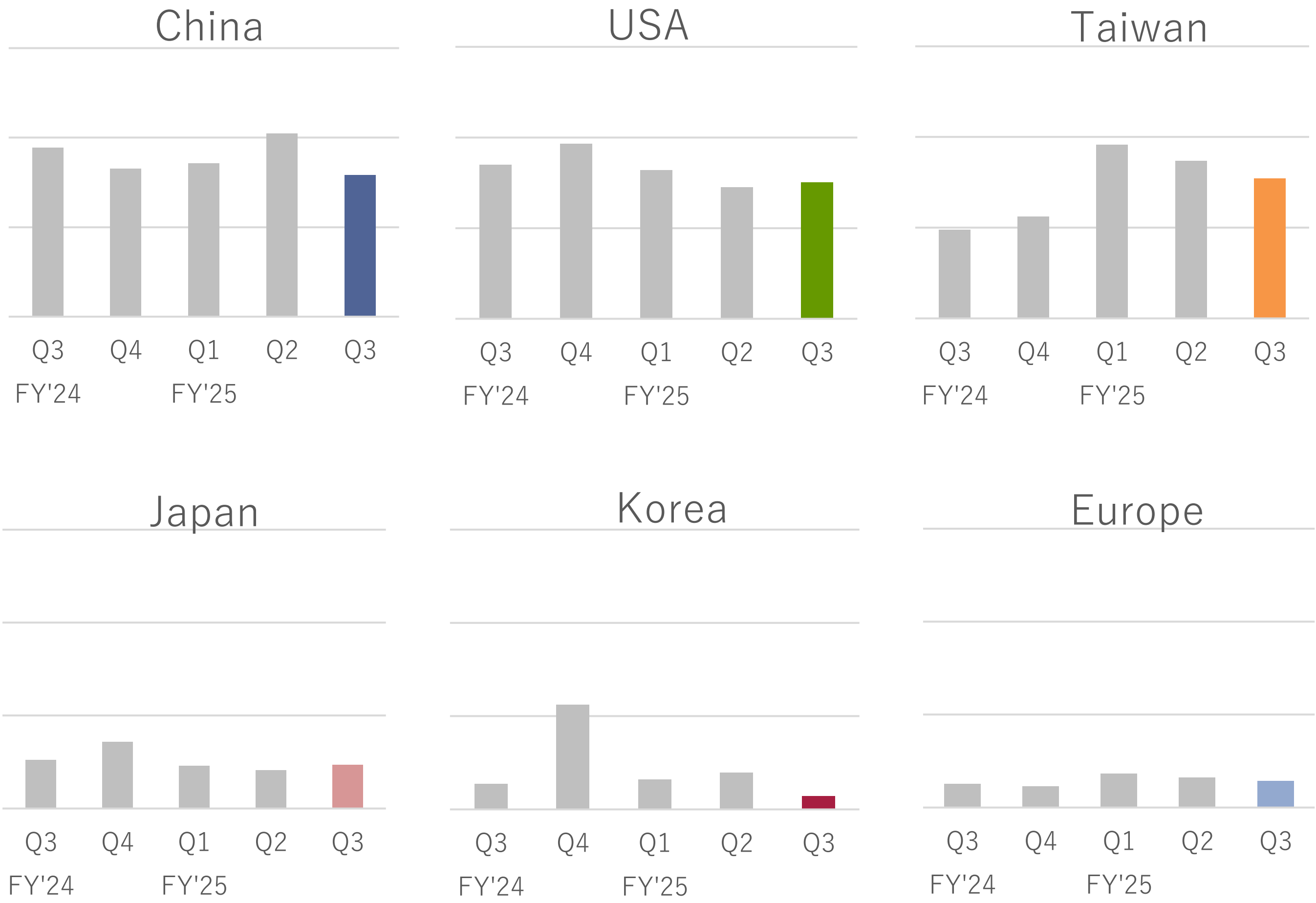
(Million JPY)	Q3 FY'24	Q4	Q1 FY'25	Q2	Q3
■ Service/Parts etc.	2,258	2,537	3,058	2,827	2,424
■ Life science	171	568	110	255	103
■ FPD	496	4,705	1,001	2,257	690
■ Analysis device	764	1,618	660	780	769
■ Semi	25,316	25,740	28,230	26,420	24,893

※ Part of the sales previously classified as “Service/Parts etc.” becomes included in “Analysis device” in FY’25 , and the figures for FY’24 have been revised accordingly.

Net sales by regions

- The rankings and composition ratios by major region unchanged
- Semi sales to equipment manufacturers increased in USA and decreased in China, sales to Taiwan declined after the growth cycle peaked while remaining at a high level

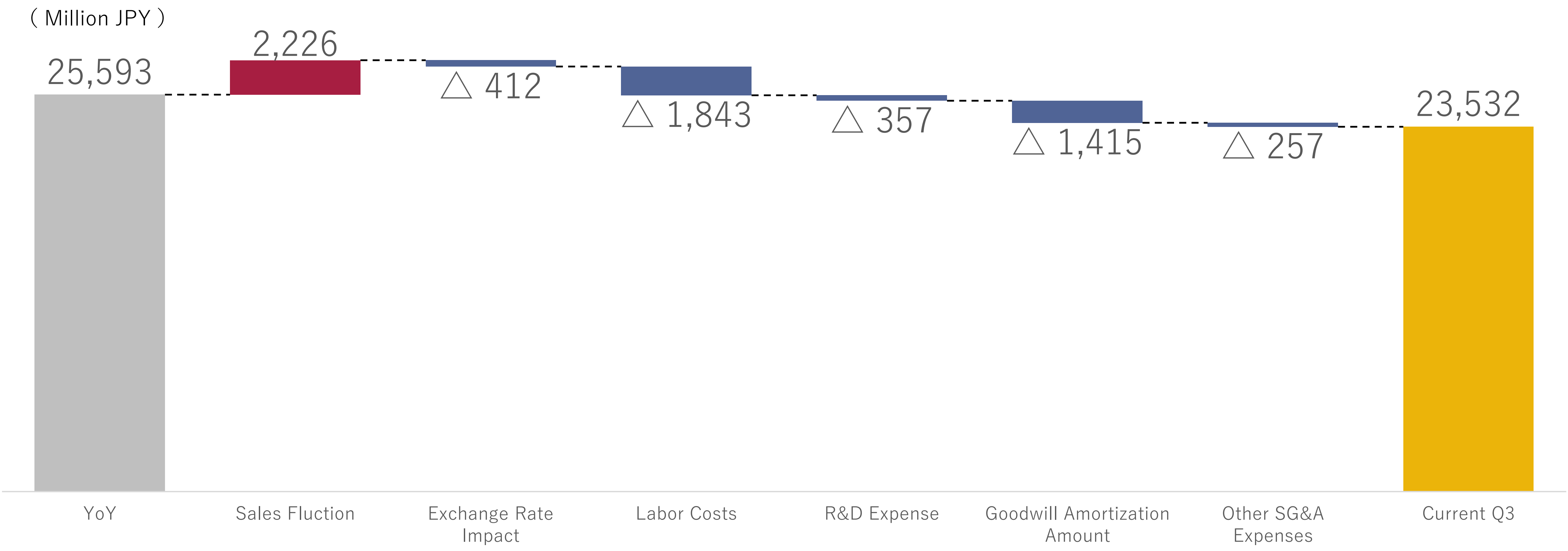




※"Net sales by region" is calculated based on the location of each customer's head quarter

Operating profit

- Operating profit declined with exchange rate effects and the increased SG&A by personnel costs and goodwill amortization at subsidiaries, while sales increased mainly in Semi

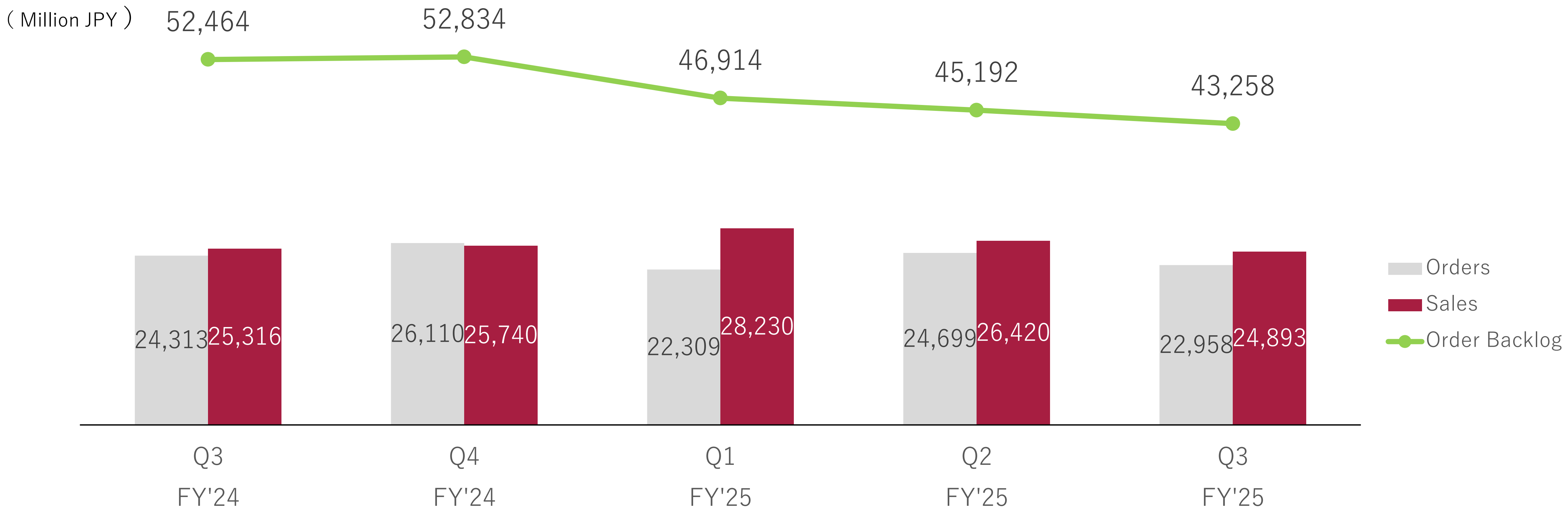


※ The impact of Nanoverse on consolidated operating profit（Million JPY）：
Labor Costs 1,385, R&D Expense 62, Goodwill amortization amount 2,100, Other SG&A Expense 1,105

Trends in orders, sales, and backlog

Semi

- Sales to Chinese equipment manufacturers and Taiwanese foundries decreased, while sales to equipment manufactures in USA increased
- Orders increased in USA and Korea, while orders from Taiwanese foundries temporarily declined due to a gap in ordering activity

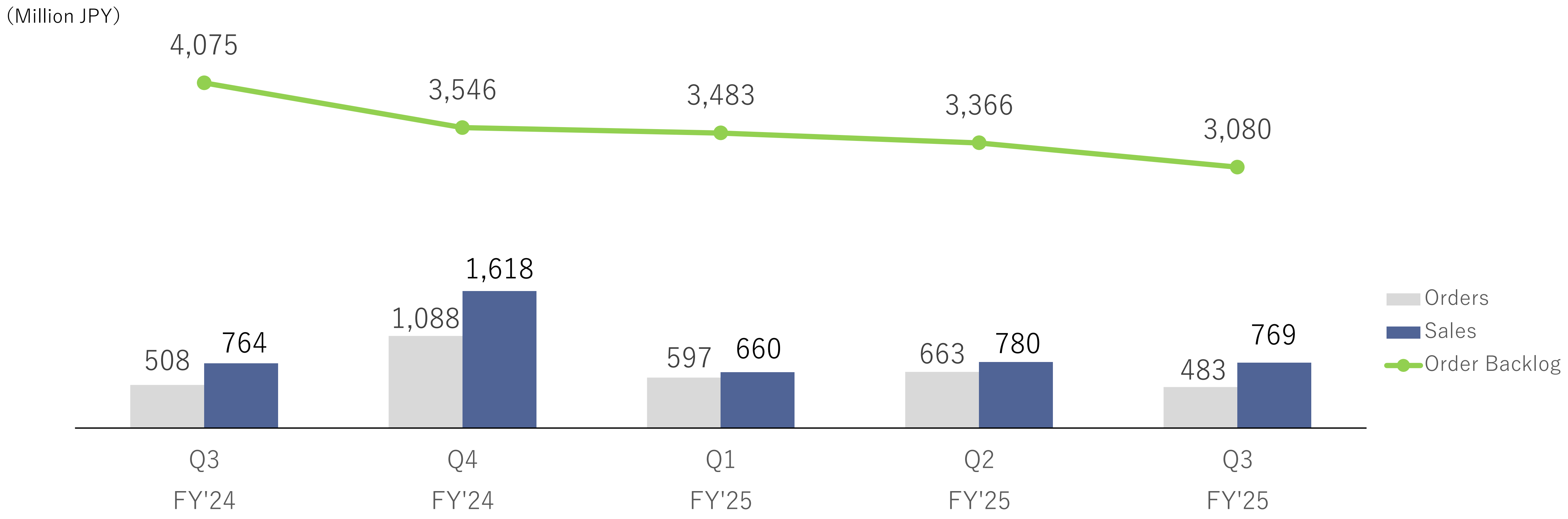


Trends in orders, sales, and backlog

RORZE

Analysis device

- Orders were delayed due to deferred customer capex plans, while the business environment is leveling off
- The Expert_LA laser ablation system, introduced two years ago, is highly regarded for advanced semiconductor processes and continues to gain traction in new orders

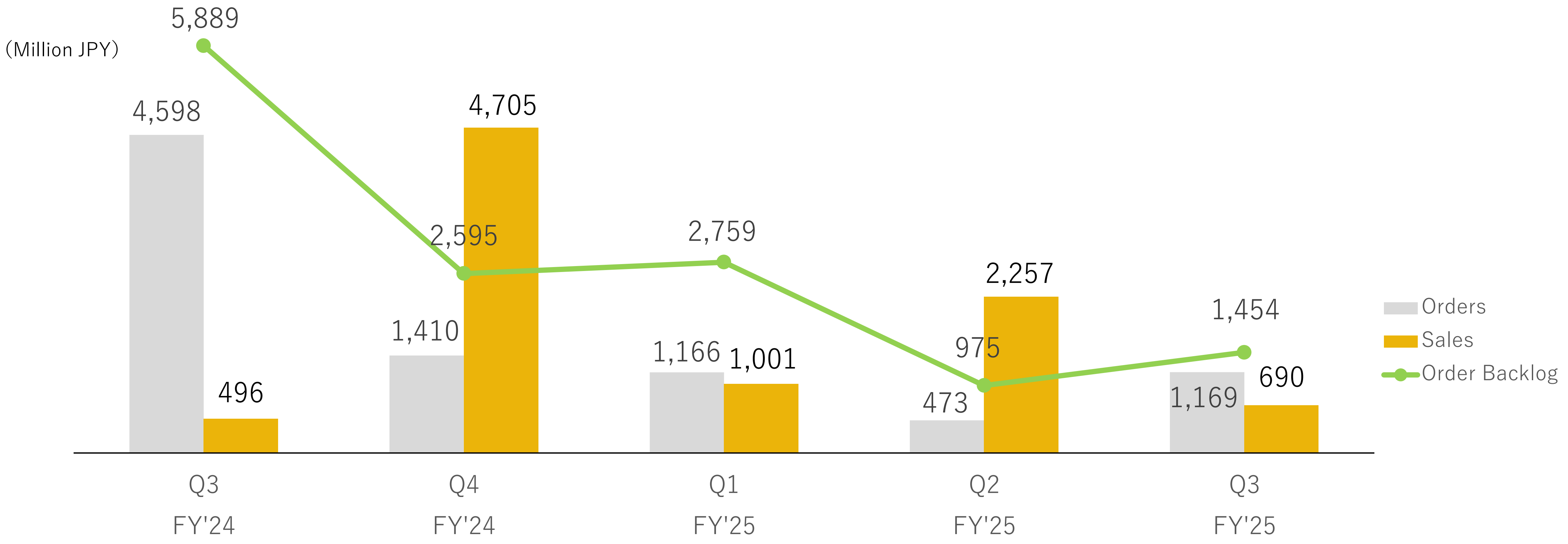


※ Part of the sales previously classified as "Service/Parts etc." becomes included in "Analysis device" in FY'25 , and the figures for FY'24 have been revised accordingly.

Trends in orders, sales, and backlog

FPD

- Sales amount declined as equipment delivery shifted to Q4 FY2025
- Order volume increased during the current quarter, while new orders declined after Q4 FY2024 due to progress in equipment deliveries

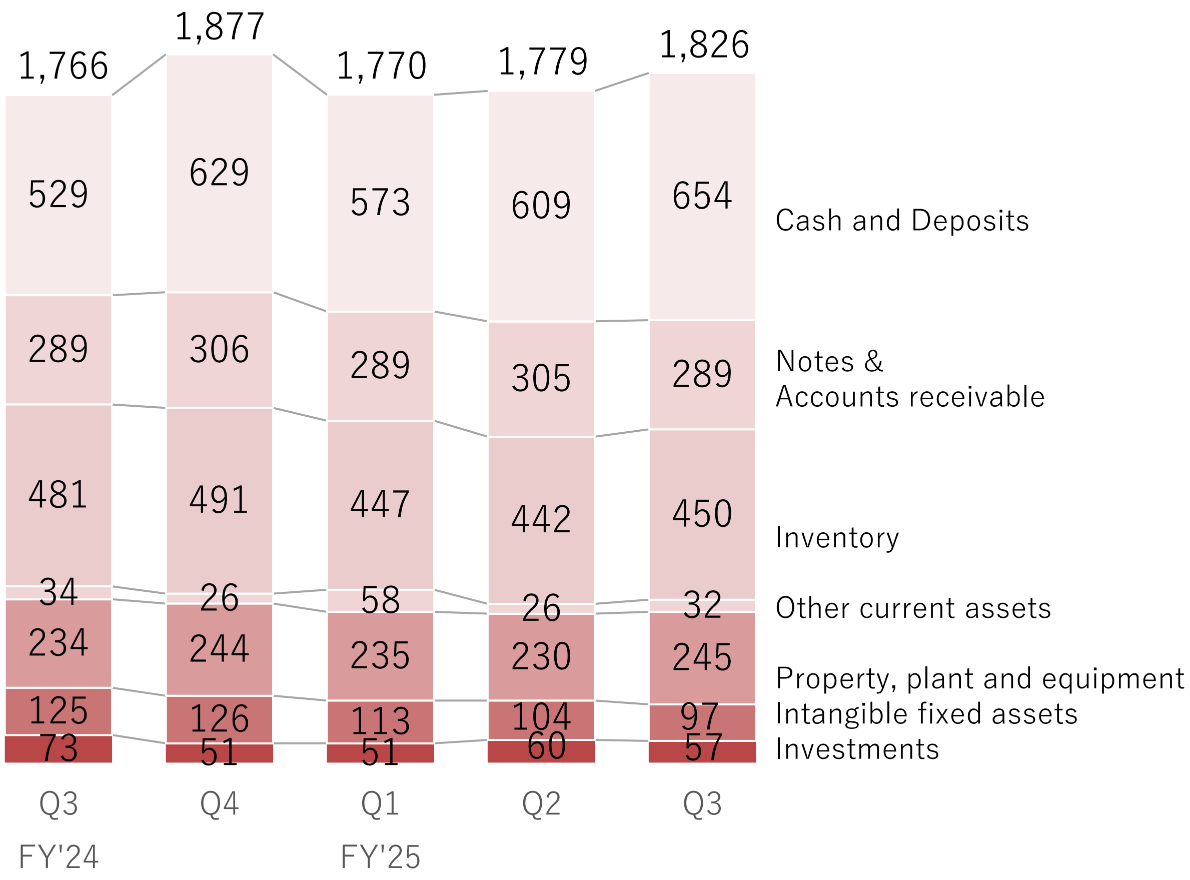


Consolidated balance sheet

- Cash and deposits were retained for business investments, while interest-bearing debt decreased by 6.5 billion JPY and a 5 billion JPY share buyback was completed by the end of July

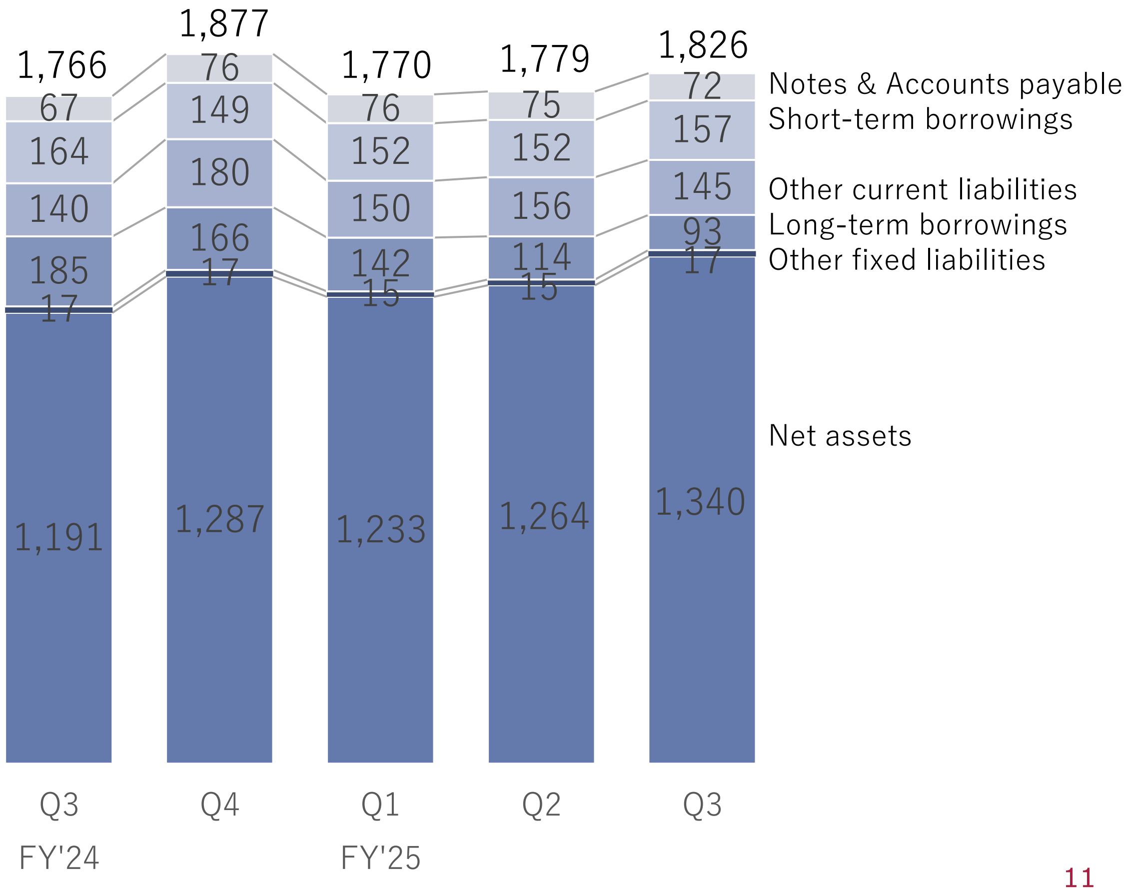
Assets

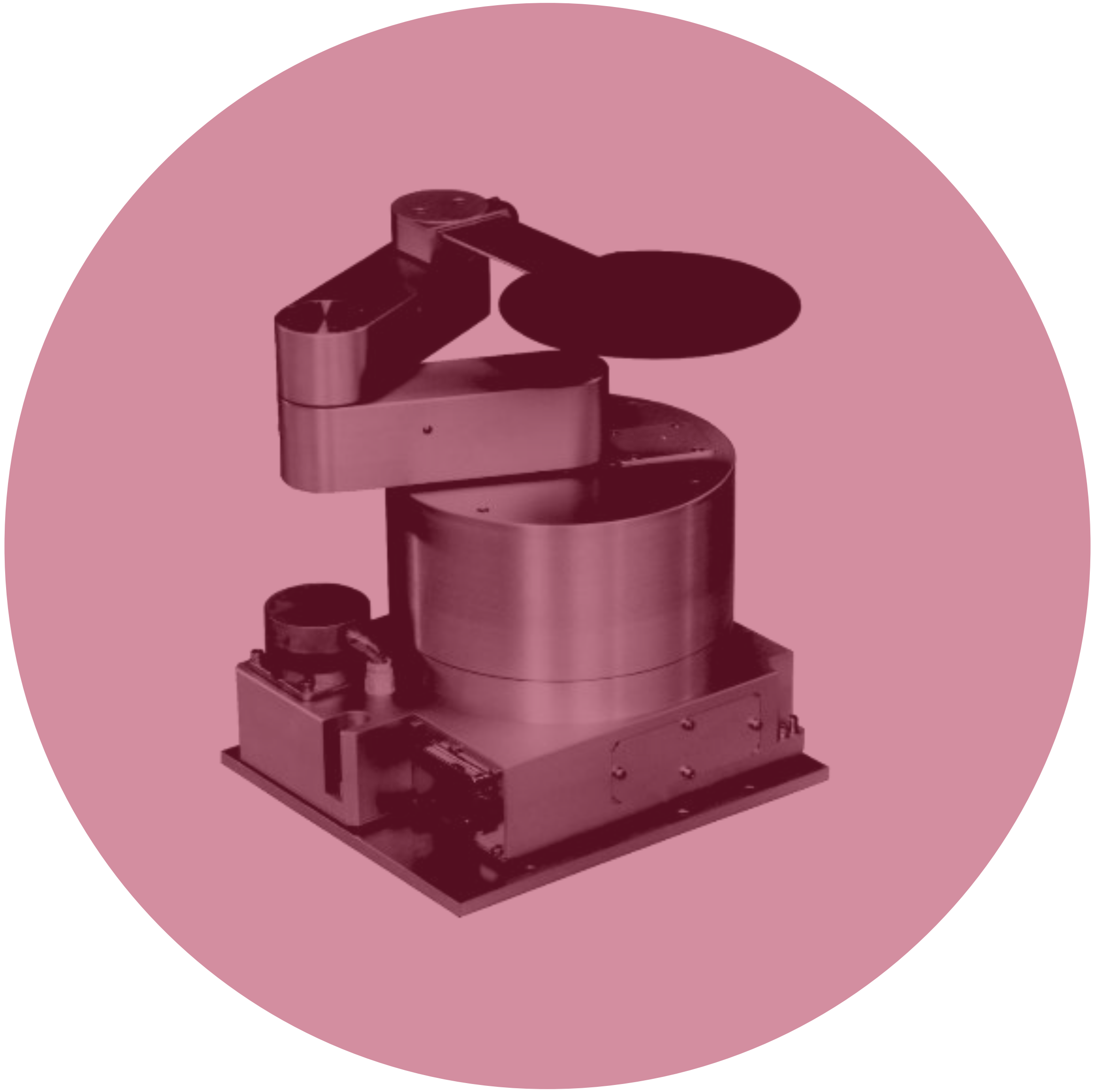
(Billion JPY)



Liabilities/Net assets

(Billion JPY)





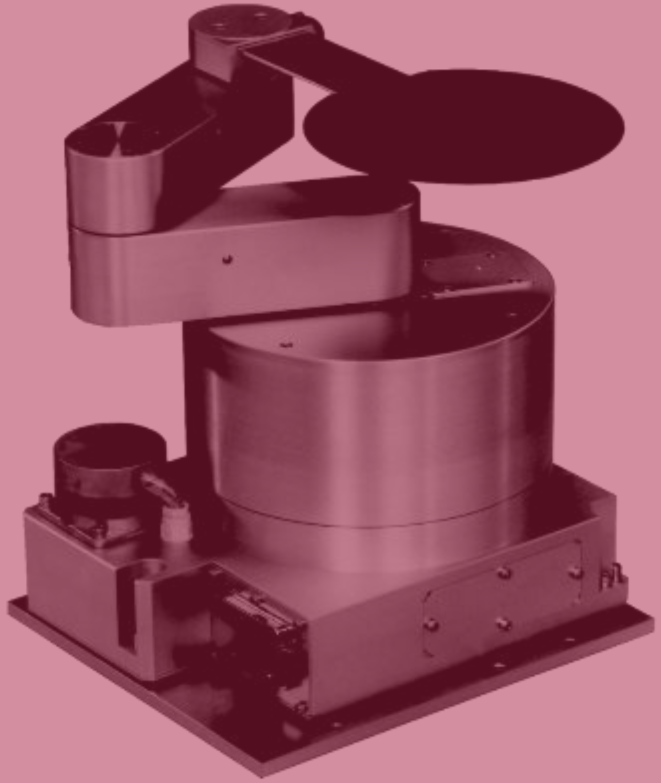
FY2025
Business Forecast

FY2025 Progress against business forecasts

- Continue to focus on achieving the full-year consolidated earnings forecast
- Driven by growing demand for generative AI, new capital investments for advanced process are increasing and expected to expand further
- Orders and sales of key substrate transfer systems, such as EFEM and Wafer Sorter, expected to rise after Q4 FY2025

（Million JPY）

	FY'25 Q3 Achievement	FY'25 Full-year Forecast	Full-year Forecast Progress rate(%)
Net Sales	94,483	128,190	73.7
Semi	79,544	106,893	74.4
Analysis device	2,210	4,163	53.1
FPD	3,949	6,550	60.3
Life science	469	1,590	29.5
Service/Parts etc.	8,310	8,992	92.4
Operating Profit	23,532	30,345	77.6
Ordinary Profit	23,375	30,618	76.3
Profit attributable to owners of parent	17,465	23,499	74.3



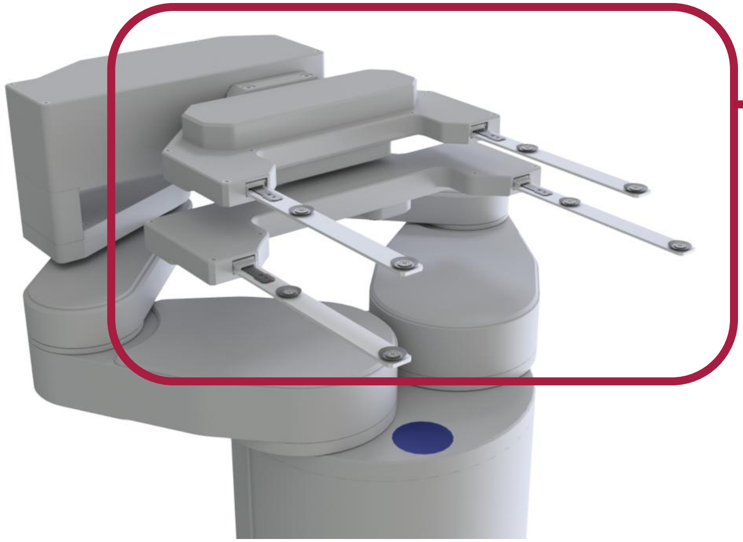
Topics

Honored to receive Supplier Award from Yield Engineering Systems

RORZE AUTOMATION, INC, the US subsidiary of RORZE CORPORATION, received the “2025 Supplier of the Year (Automation) Award” from Yield Engineering Systems

Yield Engineering Systems, based in USA, provides surface treatment, heat treatment, and deposition equipment for semiconductor manufacturing processes

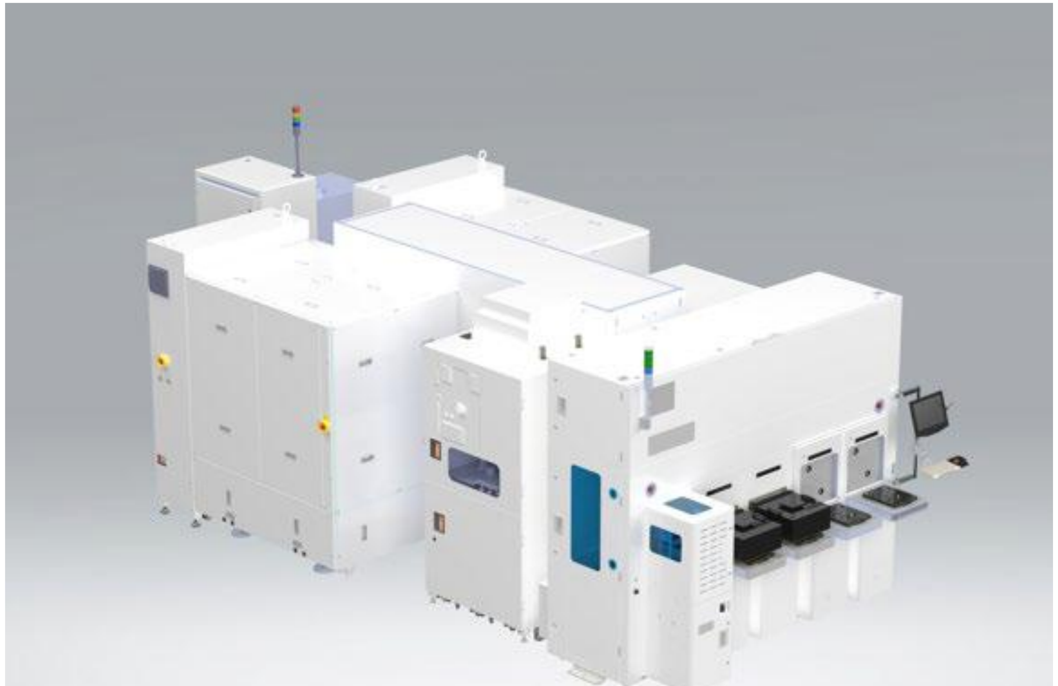
Exhibited Flap Wrist at SEMICON Japan

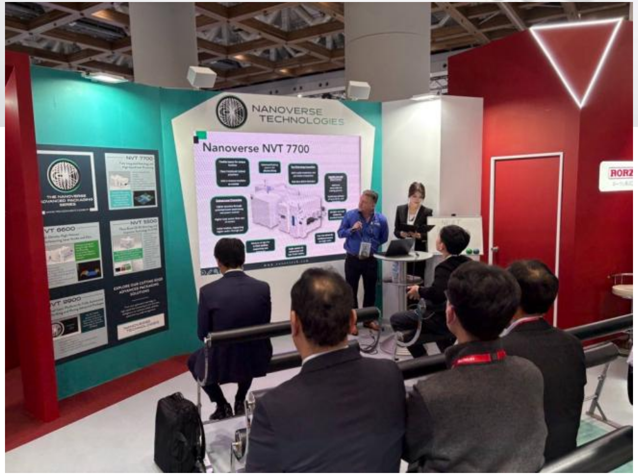


Flap Wrist (Patent Pending)

- Achieves clean transfer by holding and flattening highly curved wafers before transportation
- Movable vacuum finger with four pads adapts to wafer shape, allowing transport of three types of semiconductor wafers: standard, warped, and ultra-thin
- No hand change required for different wafer types
- Capable of flipping wafers during transfer

“Laser Scribing System” Debut (Nanoverse Technologies Ltd.)





NVT 7700

A fully integrated laser singulation and metrology system

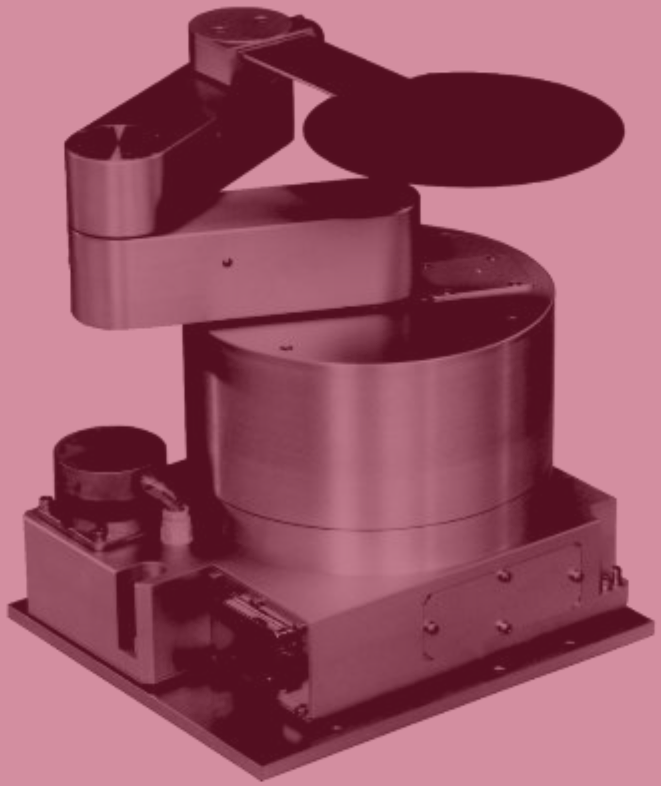
- Ideal laser scriber and dicing with a proprietary laser
- Industry-leading precision and high throughput
- Supports multi-shuttle chips

  ※ integrating multiple chips into a single IC package

- Industry-leading chip (die) strength

  –Three times stronger than competitors

- Industry-first 3D real-time measurement capability



References

Semi

Unit


Atmospheric Robot


Aligner


Load Port

System


EFEM


Vacuum Platform

System


Wafer Sorter


N2 Purge Wafer Stocker

Equipment manufacturers(SPE)

Process equipment

Inspection equipment

End -user

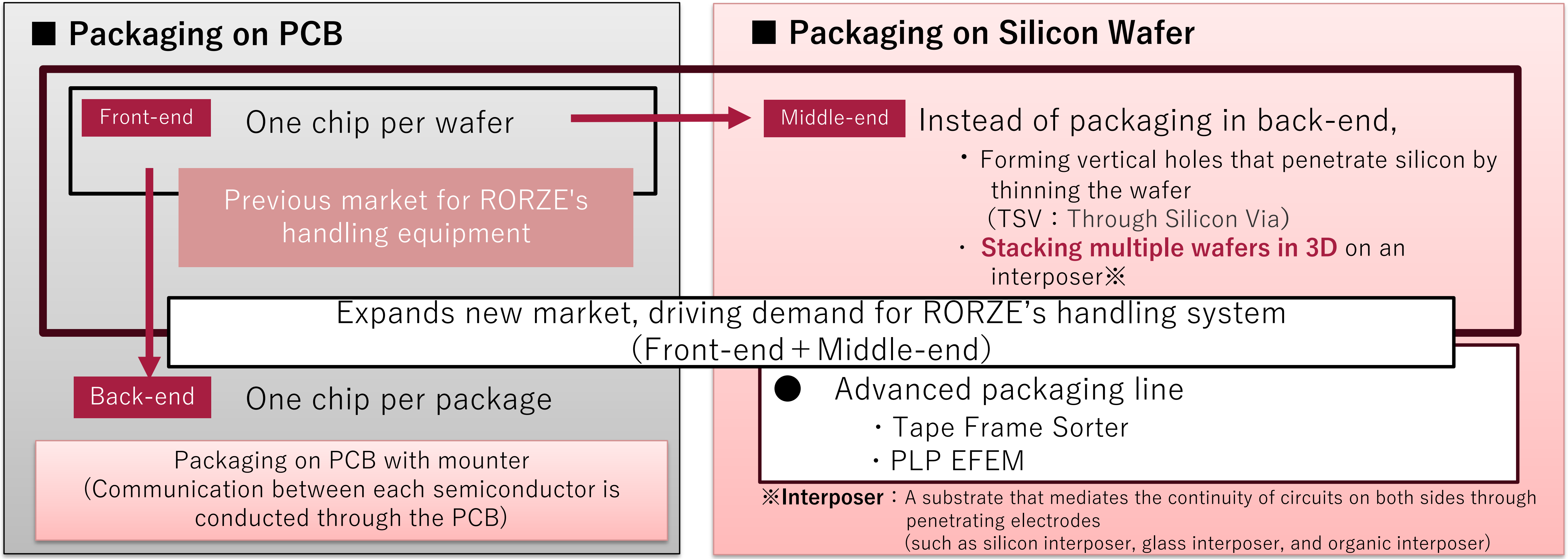
Device manufacturers

Wafer manufacturers

Advanced packaging line

Advanced packaging

Method for connecting chiplet to achieve higher device density and functionality expansion with a smaller footprint



■ Packaging on PCB

Front-end One chip per wafer

Previous market for RORZE's handling equipment

Back-end One chip per package

Packaging on PCB with mounter
(Communication between each semiconductor is conducted through the PCB)

■ Packaging on Silicon Wafer

Middle-end Instead of packaging in back-end,

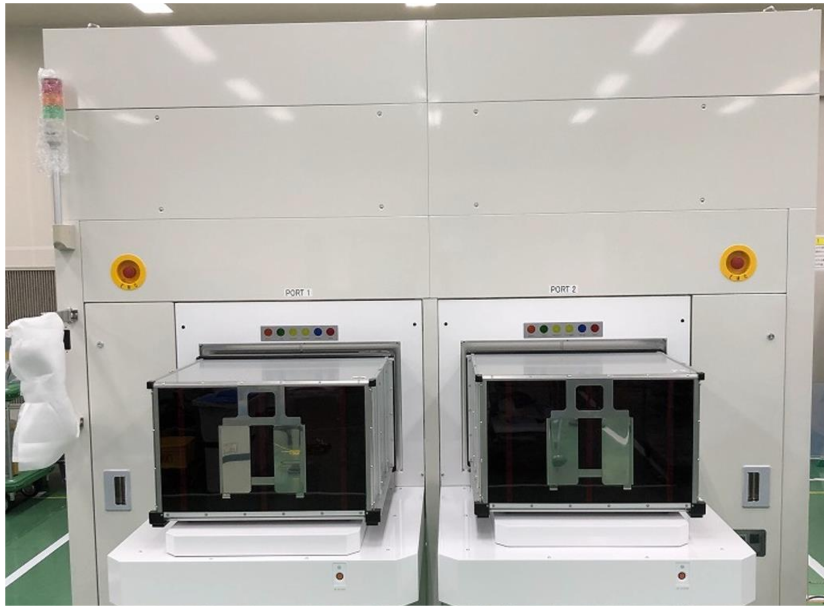
- Forming vertical holes that penetrate silicon by thinning the wafer
  （TSV：Through Silicon Via）
- **Stacking multiple wafers in 3D** on an interposer※

Expands new market, driving demand for RORZE's handling system
（Front-end＋Middle-end）

● Advanced packaging line
- ・Tape Frame Sorter
- ・PLP EFEM

※**Interposer**：A substrate that mediates the continuity of circuits on both sides through penetrating electrodes
(such as silicon interposer, glass interposer, and organic interposer)

Advanced packaging line



PLP EFEM

Tape Frame Sorter

Analysis device

RORZE IAS INC.

Gas


GED_SEMI


GED_Q


GED

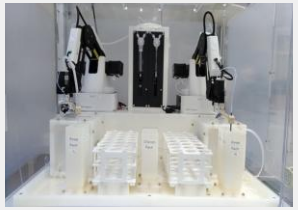

GPD

Chemical solution


ASAS Ⅱ


MSAG


CSI


ASDM

Wafer


Expert


LAGM/Expert LA

Semiconductor industry

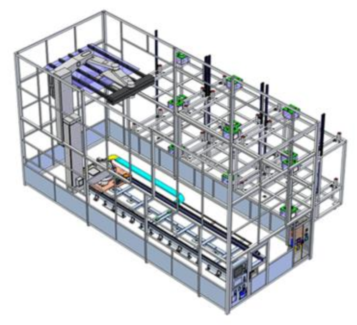
- SPEs
- End-user
  - Device manufacturers
  - Wafer manufacturers

Other industry

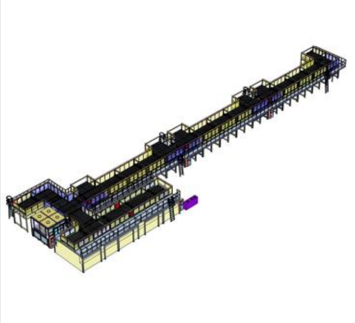
- Research institution
- Environmental measuring
- Instrument manufacturer
- Chemical manufacturer etc.

FPD

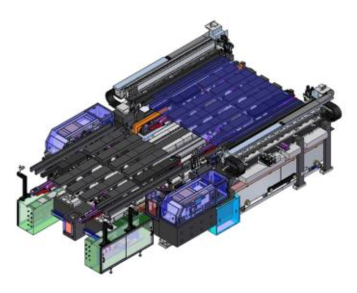
RORZE SYSTEMS
(Subsidiary in Korea)



INDEX extra-large substrate transfer system



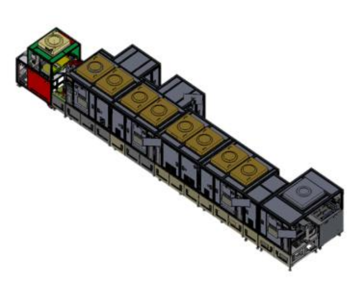
In-line returnable transfer system



Laser cutting equipment

Front-end：

FPD manufacturers
Glass for FPD manufacturers



Display module equipment

Cell type extra-large packing equipment

Back-end：

FPD manufacturers

Life science

RORZE

RORZE
LS Lifescience

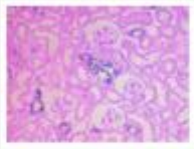

Incubator
SCALE48


CO₂ Incubator with medium exchange function＆cell imaging function
CellKeeper® II 48Plus


Mobile robot


Automatic medium exchange system
CellFarm(L)-360™


Scheduling software
Green Button Go^{TM} ※
(※Product of Biosero)


tissue staining and
gene function analysis
GenoStaff

Drug discovery, Regenerative medicine (universities, pharmaceutical companies)

RORZE